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Thermal standardization on semiconductor packages -
Part 6: Thermal resistance and capacitance model for transient temperature
prediction at junction and measurement points

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**Thermal standardization on semiconductor packages -
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temperature prediction at junction and measurement points**

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The text of this International Standard is based on the following documents:

Draft	Report on voting
47D/991/CDV	47D/998/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.